

FORM PTO-1449 (Rev. 2-32)	U. S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE	ATTY. DOCKET NO. EN995141V	SERIAL NO To Be Assigned
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## U.S. PATENT DOCUMENTS

Exmr Initial	Document Number	Date	Name	Class	Sub Class	Filing Date
JHA	4,925,525	05/15/90	Oku et al.			
JHA	4,980,217	12/25/90	Grundfest et al.			
JHA	5,004,639	04/02/91	Desai			
JHA	5,050,038	09/17/91	Malaurie et al.			
JHA	5,114,518	05/19/92	Hofarth et al.			
JHA	5,252,195	10/12/93	Kobayashi et al.			
JHA	5,277,787	01/11/94	Otani et al.			
JHA	5,288,542	02/22/94	Cibulsky et al.			
JHA	5,418,689	05/23/95	Alpaugh et al.			
JHA	5,468,999	11/21/95	Lin et al.			
JHA	5,521,332	05/28/96	Shikata et al.			
JHA	5,500,555	03/19/96	Ley			
JHA	5,625,225	12/22/93	Huang et al.			
JHA	5,485,038	01/16/96	Licari et al.			
JHA	5,598,031	06/23/93	Groover et al.			
JHA	3,777,220	12/04/73	Tatusko et al.			
JHA	4,404,059	09/13/83	Livshits et al.			
JHA	4,769,270	09/06/88	Nagamatsu et al.			
JHA	5,590,030	01/10/90	Kametani et al.			
JHA	4,191,800	03/04/80	Holtzman			

OTHER DOCUMENTS  
(Including Author, Title, Date, Pertinent Pages, Etc.)

JHA	1)	"Chapter 12: Printed Circuit Board Packaging," <i>Microelectronics Packaging Handbook</i> , Tummala, Rao R., et al., Editors, and Klopfenstein, Alan G., Managing Editor, Van Nostrand Reinhold (New York) 1989, pp. 863-921.
	2)	"Electrochemical Migration in Multichip Modules," Rudra, B., et al., <i>Circuit World</i> , Vol. 22, No. 1, 1995, pp. 67-70.
	3)	"Microstructure of Conductive Anodic Filaments Formed during Accelerated Testing of Printed Wiring Boards," Ready, W. J., et al., <i>Circuit World</i> , Vol. 21, No. 4, 1995, pp. 5-9

Examiner	<i>Jose H. Alcalde</i>	Date Considered
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Examiner: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.